

LINEAR TECHNOLOGY MATERIALS DECLARATION

ltc3101euf#pbf

(Engineering Calculation)

QFN 4mm X 4mm Exp. Pad

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TOTAL MASS (g) : 0.041136

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.002105 | 1000000 | 51172.3359375 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.015961 | 975000 | 388010.28125 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000393 | 24000 | 9553.7890625 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000005 | 300 | 121.549484253 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000011 | 700 | 267.408874512 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.016370 | 1000000 | 397953.03125 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.000773 | 1000000 | 18779.5703125 | | |
| | | External Plating Total: | | | | 0.000773 | 1000000 | 18779.5703125 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000362 | 1000000 | 8800.18261719 | | |
| | | Internal Plating Total: | | | | 0.000362 | 1000000 | 8800.18261719 |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000934 | 750000 | 22705.4453125 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000311 | 250000 | 7560.37841797 | | |
| Die Attach Total: | | | | 0.001245 | 1000000 | 30265.8222656 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.002616 | 130000 | 63594.6914062 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.017303 | 860000 | 420634.15625 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000201 | 10000 | 4886.28955078 | | |
| | | Encapsulation Total: | | | | 0.020120 | 1000000 | 489115.15625 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000161 | 1000000 | 3913.89331055 | | |
| | | | | | TOTAL MASS (g) : | 0.041136 | | |